

## ABSTRACT OF THE INVENTION

The present invention relates to a device that includes a low-ohmic test. The device includes a metallization copper pad such as metal-six, a metal first film such as Ni that is disposed above the metallization copper pad, and a metal second film such as Au that is disposed above the metal first film. The present invention also relates to a wire-bonding process, and to a method of pulling a first wire bond and making a second wire bond.

"Express Mail" mailing label number: EV019077117US

Date of Deposit: January 16, 2002

This paper or fee is being deposited on the date indicated above with the United States Postal Service pursuant to 37 CFR 1.10, and is addressed to the Commissioner for Patents, Box Patent Application, Washington, D.C. 20231.